Product End-of-Life Disassembly Instructions

**Product Category:** Commercial Display

**Marketing Name / Model**
[List multiple models if applicable.]

HP U160 15.6-inch LED Backlit Monitor

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm I/F Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>USb cable</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#1</td>
</tr>
<tr>
<td>Description #2 SCREW DRIVER(PHILLIPS HEAD)</td>
<td>#2</td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove Cover From Display Head
2. Remove Rear Cover From Display Head
3. Remove Shielding Cover From Display Head
4. Remove Acetate Tape From Display Head
5. Remove Interface Board From Display Head
6. Remove Main Bracket From Display Head
7. Remove Front Cover From Display Head
8. Remove Rubber From Front Cover
9. Remove Bracket From Panel
10. Remove LVDS Wire From Interface Board
11. Remove Mylar and Gasket From Shielding Cover
12. Remove Gasket From Main Bracket
13. LCD Panel explode

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP U160 Disassembly Process

- Guangguo Cheng
- Mechanical Engineer
- Oct-11-2012
External Electric Cable Dissecting Process

1. Remove USB Cable From Display Head.

2. Dissecting To Complete.

USB Cable
3. Remove 4pcs screws.

4. Remove Cover From Display Head.
5. Remove Rear Cover From Display Head.
Remove Shielding Cover From Display Head

6. Remove 5pcs screws.

7. Remove Shielding Cover From Display Head
Remove Acetate Tape From Display Head

8. Remove Acetate Tape From Display Head
Remove Interface Board From Display Head

9. Remove Interface Board From Display Head

Remove LVDS Wire
10. Remove Main Bracket From Display Head
11. Remove Front Cover From Display Head

Remove panel From the Snap of Front Cover
Remove Rubber From Front Cover

12. Remove Rubber From Front Cover
Remove Bracket From Panel

13. Remove 4pcs Screws

14. Remove Bracket From Panel
15. Remove LVDS Wire From Interface Board
16. Remove Mylar and Gasket From Shielding Cover
17. Remove Gasket From Main Bracket
LCD PANEL EXPLODE

組裝程序:
1. 將遮光Masking Tape沿TFT polarizer 邊緣貼於TFT上。
2. 將TFT polarizer 保護膜片撕離。
3. 將panel assy放置於backlight unit中，放置時以下側為基準，接著反折PCB。
4. 將PCB卡入膠框上方與右方固定處。
5. 將FPC 插入PCB上之LED connector。
6. 將模組翻轉至正面後(不可以用手翻轉模組)，將polarizer CP保護膜片撕離。
7. 將鐵框焊接於COF端後與backlight unit 焊合後再往下組立。
8. 確實將鐵框上之扣爪(左右各4處,非COF端4處)與backlight unit卡緊。
9. 將polarizer CP 保護膜片貼回。
10. 模組翻轉至背面後，將Grounding Tape貼於PCB天線接地膠條區，首先對齊PCB 接觸區往側邊鐵框貼平。

注意事項:
1. 將polarizer 保護膜片撕離時務必注意靜電保護，避免損傷IC受損。
2. 將覆膜撕離時務必注意靜電保護(帶靜電手環)，避免LED受損。
3. 組立前注意backlight unit 光學膜片是否有異位。
4. Panel四角皆必須置入backlight unit中，PCB組裝後不可移動panel。
5. PCB反折時須注意panel與backlight unit位置不可偏離或造成COF拉曲變形。
6. COF不可往反方向折彎。
7. 確實檢查鐵框上方扣爪與lamp cover卡勾是否確實卡緊。
8. 鐵框左右兩側扣爪是否確實扣緊backlight unit卡勾。
9. IF connector 務必於Protector film 窗口外露。
10. Grounding Tape 勿覆蓋PCB板上之任一component.